

Amendments to the Claims

1. *(Currently Amended)* A wafer ~~(1)~~, which wafer ~~(1)~~ comprises a number of exposure fields ~~(2)~~ and which wafer ~~(1)~~ comprises a number of lattice fields ~~(3)~~ in each exposure field ~~(2)~~, wherein each lattice field ~~(3)~~ contains an IC ~~(4)~~, and which wafer ~~(1)~~ comprises a first group ~~(5)~~ of first dicing paths ~~(6)~~ and a second group ~~(7)~~ of second dicing paths ~~(8)~~, wherein all of the first dicing paths ~~(6)~~ of the first group ~~(5)~~ run parallel to a first direction ~~(X)~~ and have a first path width ~~(W1)~~ and wherein all of the second dicing paths ~~(8)~~ of the second group ~~(7)~~ run parallel to a second direction ~~(Y)~~ intersecting the first direction ~~(X)~~ and have a second path width ~~(W2)~~, and wherein the first dicing paths ~~(6)~~ and the second dicing paths ~~(8)~~ are provided and designed for a subsequent segregation of the lattice fields ~~(3)~~ and the ICs ~~(4)~~ contained therein, and wherein in each exposure field ~~(2)~~ at least two control module fields ~~(A1, A2, A3, A4, B1, B2, B3, B4, C2, C4, D2, D4, E1, E3, F1, F3, G2, H1, J1)~~ are provided, each of which control module fields ~~(A1, A2, A3, A4, B1, B2, B3, B4, C2, C4, D2, D4, E1, E3, F1, F3, G2, H1, J1)~~ contains at least one optical control module ~~(OCM A1, OCM A2, OCM A3, OCM A4, OCM B1, OCM B2, OCM B3, OCM B4, OCM C2, OCM D4)~~, and wherein each control module field ~~(A1, A2, A3, A4, B1, B2, B3, B4, C2, C4, D2, D4, E1, E3, F1, F3, G2, H1, J1)~~ provided in an exposure field ~~(2)~~ is provided in place of a preset number of lattice fields ~~(3)~~, and wherein the at least two control module fields ~~(A1, A2, A3, A4, B1, B2, B3, B4, C2, C4, D2, D4, E1, E3, F1, F3, G2, H1, J1)~~ of each exposure field ~~(3)~~ are arranged at an average distance ~~(K)~~ from one another extending in the second direction ~~(Y)~~, which average distance ~~(K)~~ is equal to at least a quarter of the side length ~~(L)~~ of a side ~~(M)~~ of the exposure field ~~(2)~~ which extends in the second direction ~~(Y)~~.

2. *(Currently Amended)* A wafer ~~(1)~~ as claimed in claim 1, wherein the average distance ~~(K)~~ is equal to the whole side length ~~(L)~~ of a side ~~(M)~~ of the exposure field ~~(2)~~ which extends in the second direction ~~(Y)~~ minus the side length ~~(N)~~ of a side ~~(P)~~ of a lattice field ~~(3)~~ which extends in the second direction ~~(Y)~~.

3. *(Currently Amended)* A wafer ~~(1)~~ as claimed in claim 1, wherein each exposure field ~~(2)~~ is designed rectangular, and wherein four control module fields

~~(A1, A2, A3, A4, B1, B2, B3, B4, C2, C4, D2, D4, E1, E3, F1, F3, G2, H1, J1)~~ are provided in each exposure field ~~(2)~~, and wherein each control module field ~~(A1, A2, A3, A4, B1, B2, B3, B4, C2, C4, D2, D4, E1, E3, F1, F3, G2, H1, J1)~~ is located in a corner region of the exposure field ~~(2)~~ in question.

4. *(Currently Amended)* A wafer ~~(1)~~ as claimed in claim 1, wherein each control module field ~~(A1, A2, A3, A4, B1, B2, B3, B4, C2, C4, D2, D4, E1, E3, F1, F3, G2, H1, J1)~~ provided in an exposure field ~~(2)~~ is provided in place of one lattice field ~~(3)~~ only.